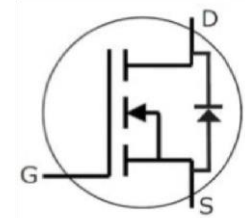
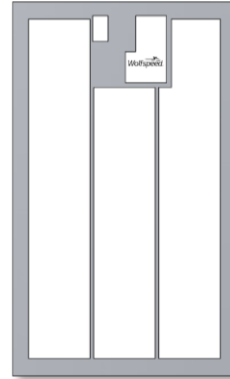


# CPM3-1700-R020E

## Wolfspeed SiC Gen 3 MOSFET

### Description

This is the Wolfspeed's 3rd generation of high performance silicon carbide MOSFET in a packageless bare die format to be implemented into any custom module design. The high blocking voltage with low on-resistance, high speed switching with low capacitance make this MOSFET ideal for high frequency switching application including industrial inverters and UPS



Package Types: Bare Die  
PN's: CPM3-1700-R020E

### Features

- Enhanced 3rd Generation SiC MOSFET
- High blocking voltage with low on-resistance
- High speed switching with low capacitance
- Fast intrinsic diode with low reverse recovery

### Applications

- EV Chargers
- UPS
- Inverters
- DC/DC Converters

### Absolute Maximum Ratings

Stress beyond those listed under absolute maximum ratings may damage the device.

Parameter	Symbol	Rating	Unit
Drain-Source Voltage, across $T_{vj}$	$V_{DS(max)}$	1700	V
Maximum Gate-Source Voltage, Peak Transient Capability	$V_{GS(max)}$	-8/+19	V
Continuous Drain Current, $V_{GS} = 15V$ , assumes die packaged in TO-247 package with $R_{th(j-c)} < 0.275 K/W$	$I_D$	$T_c = 25^\circ C$	120
		$T_c = 100^\circ C$	86
Pulsed Drain Current, $t_p$ limited by $T_{vj(max)}$	$I_{D(pulse)}$	249	A
Virtual Junction and Storage Temperature	$T_{vj}, T_{stg}$	-55 to +175	$^\circ C$
Maximum Processing Temperature, in non-reactive ambient	$T_{proc}$	325	$^\circ C$

### Recommended Operating Conditions

Parameter	Symbol	Rating	Unit
Recommended Operating Gate - Source Voltage	$V_{GS(op)}$	-4/+15	V

**Electrical Characteristics ( $T_{VJ} = 25^{\circ}\text{C}$ )**

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1700			V	$V_{GS} = 0\text{ V}$ , $I_D = 40\text{ }\mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	1.8	2.5	3.6	V	$V_{DS} = V_{GS}$ , $I_{DS} = 25.4\text{ mA}$
			2.0		V	$V_{DS} = V_{GS}$ , $I_{DS} = 25.4\text{ mA}$ , $T_{VJ} = 175^{\circ}\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$		1	40	$\mu\text{A}$	$V_{DS} = 1700\text{ V}$ , $V_{GS} = 0\text{ V}$
Gate-Source Leakage Current	$I_{GSS}$		1	250	nA	$V_{GS} = 15\text{ V}$ , $V_{DS} = 0\text{ V}$
Drain-Source On-State Resistance	$R_{DS(on)}$	12.3	17.5	22.8	m $\Omega$	$V_{GS} = 15\text{ V}$ , $I_D = 92.2\text{ A}$
			40.3			$V_{GS} = 15\text{ V}$ , $I_D = 92.2\text{ A}$ , $T_{VJ} = 175^{\circ}\text{C}$
Transconductance	$g_{fs}$		63		S	$V_{DS} = 20\text{ V}$ , $I_{DS} = 92.2\text{ A}$
			61			$V_{DS} = 20\text{ V}$ , $I_{DS} = 92.2\text{ A}$ , $T_{VJ} = 175^{\circ}\text{C}$
Input Capacitance	$C_{iss}$		7667		pF	$V_{GS} = 0\text{ V}$ , $V_{DS} = 1000\text{ V}$ $f = 100\text{ kHz}$ $V_{AC} = 25\text{ mV}$
Output Capacitance	$C_{oss}$		188			
Reverse Transfer Capacitance	$C_{rss}$		10			
$C_{oss}$ Stored Energy	$E_{oss}$		292		$\mu\text{J}$	$V_{DS} = 1000\text{ V}$ , $f = 100\text{ kHz}$
Total Internal Gate Resistance	$R_{G(total)}$	5.2	7.4	9.6	$\Omega$	$f = 1\text{ MHz}$ , $V_{AC} = 25\text{ mV}$
Gate to Source Charge	$Q_{gs}$		80		nC	$V_{DS} = 1200\text{ V}$ , $V_{GS} = -4\text{ V}/15\text{ V}$ $I_{DS} = 92.2\text{ A}$
Gate to Drain Charge	$Q_{gd}$		70			
Total Gate Charge	$Q_g$		249			

**Reverse Diode Characteristics ( $T_{VJ} = 25^{\circ}\text{C}$ )**

Characteristics	Symbol	Typ.	Max.	Unit	Test Conditions
Diode Forward Voltage	$V_{SD}$	4.9		V	$V_{GS} = -4\text{ V}$ , $I_{SD} = 41.6\text{ A}$
		4.3		V	$V_{GS} = -4\text{ V}$ , $I_{SD} = 41.6\text{ A}$ , $T_{VJ} = 175^{\circ}\text{C}$
Reverse Recovery Time	$t_{rr}$	43		ns	$V_{GS} = -4\text{ V}$ , $I_{SD} = 92.2\text{ A}$ , $V_R = 1200\text{ V}$ $\text{dif}/\text{dt} = 4000\text{ A}/\mu\text{s}$ , $T_{VJ} = 175^{\circ}\text{C}$
Reverse Recovery Charge	$Q_{rr}$	2557		nC	
Peak Reverse Recovery Current	$I_{rrm}$	87		A	

## Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

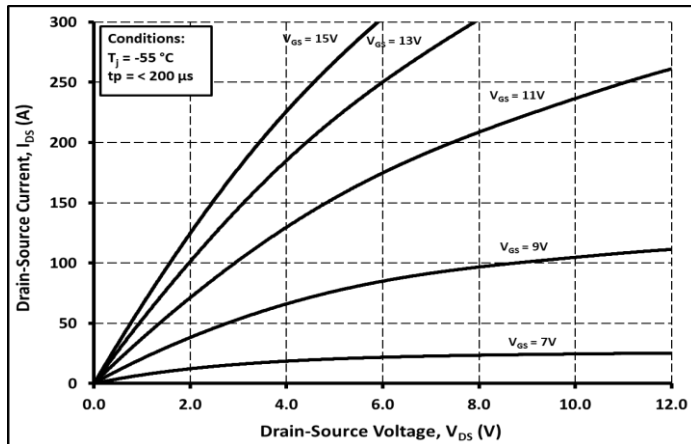


Figure 1.

Output Characteristics  $T_{vj} = -55^\circ\text{C}$

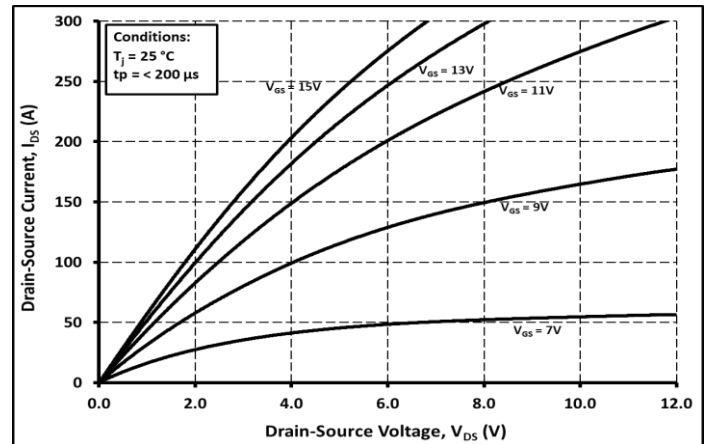


Figure 2.

Output Characteristics  $T_{vj} = 25^\circ\text{C}$

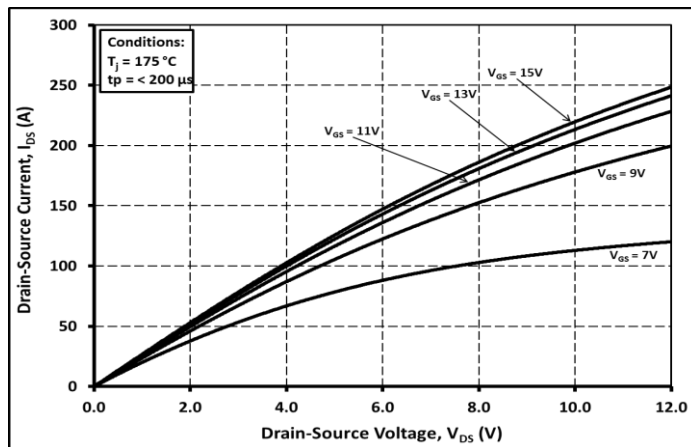


Figure 3.

Output Characteristics  $T_{vj} = 175^\circ\text{C}$

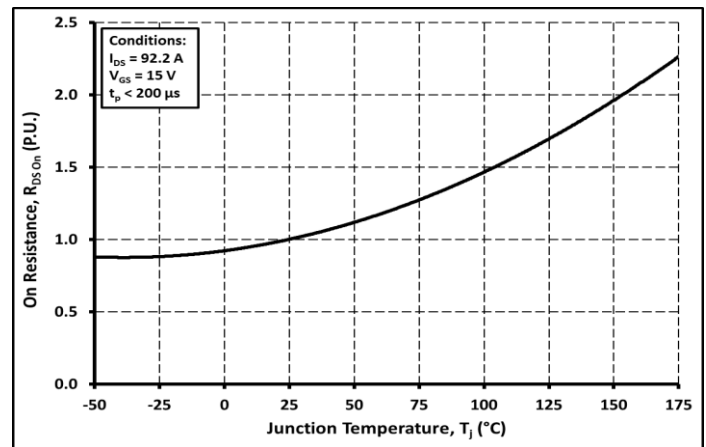


Figure 4.

Normalized On-Resistance vs. Temperature

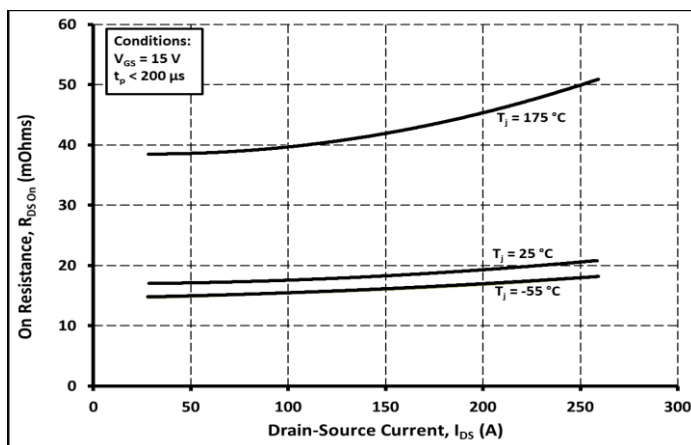


Figure 5.

On-Resistance vs. Drain Current For Various Temperatures

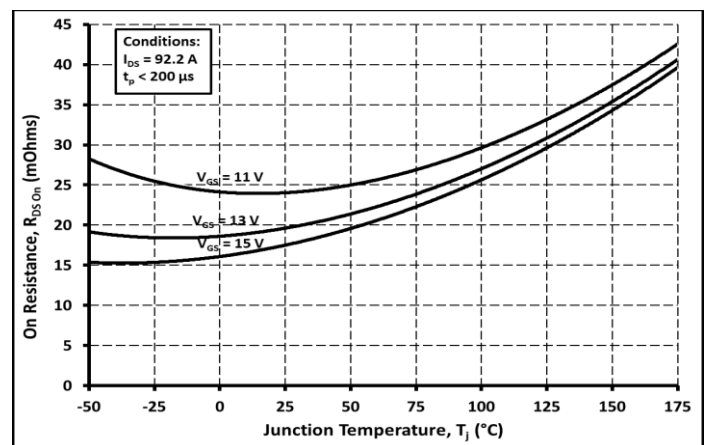


Figure 6.

On-Resistance vs. Temperature For Various Gate Voltages

## Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

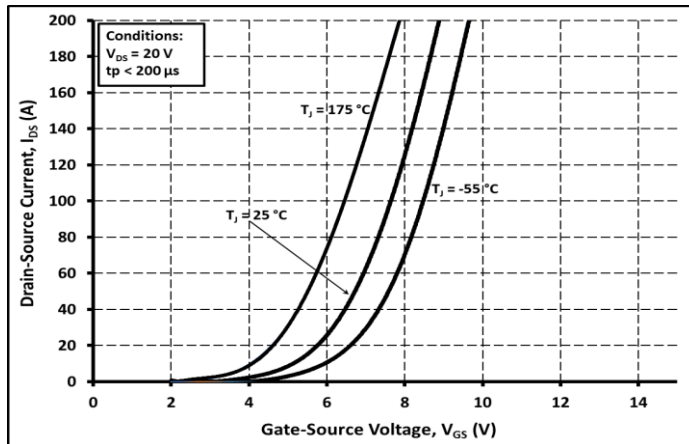


Figure 7.

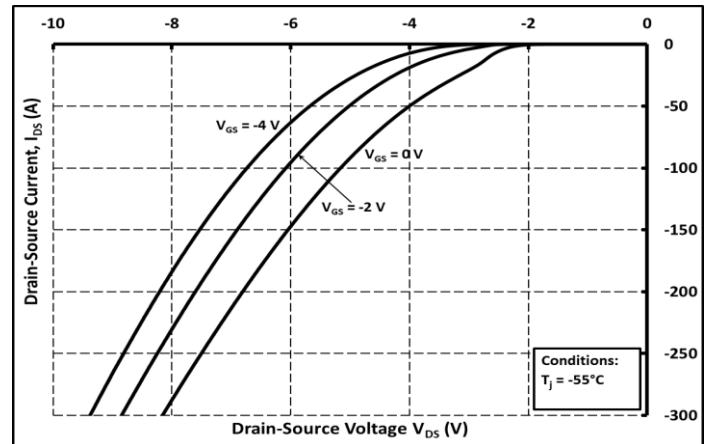


Figure 8.

Transfer Characteristic For Various Junction Temperatures

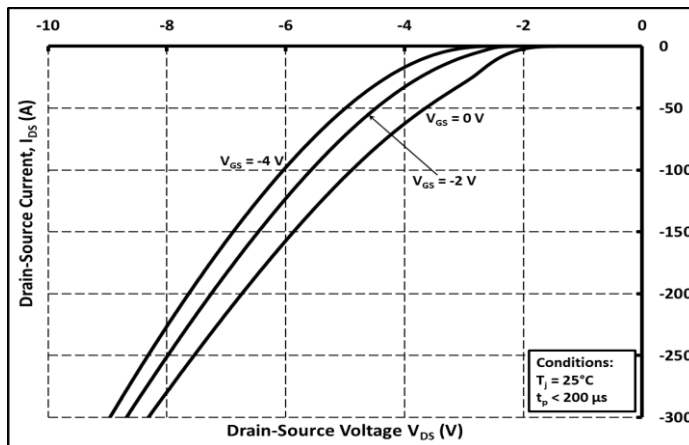


Figure 9.

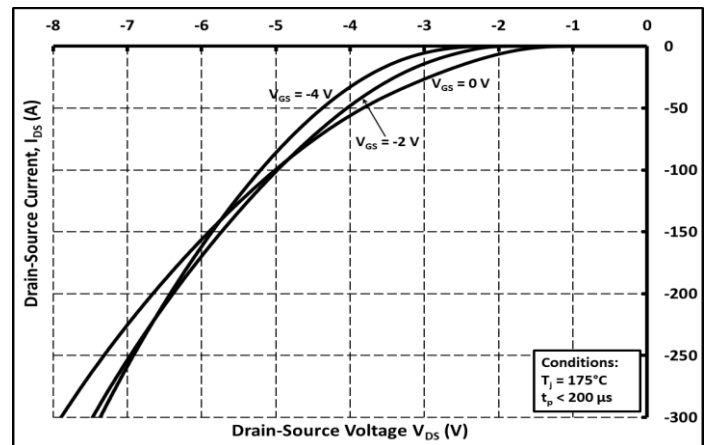


Figure 10.

Body Diode Characteristic at  $T_{vj} = 25\text{ }^{\circ}\text{C}$

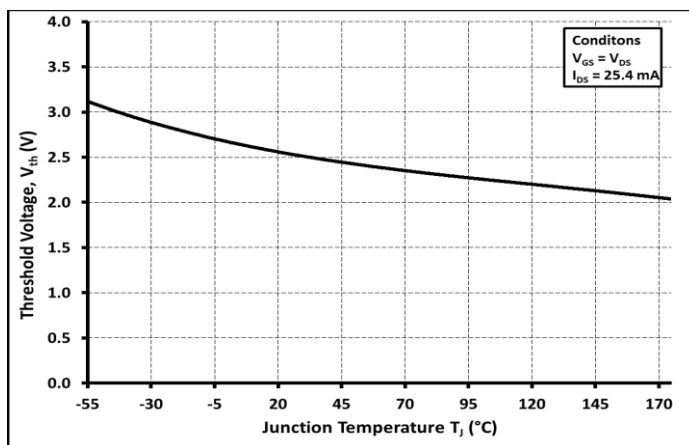


Figure 11.

Threshold Voltage vs. Temperature

Body Diode Characteristic at  $T_{vj} = 175\text{ }^{\circ}\text{C}$

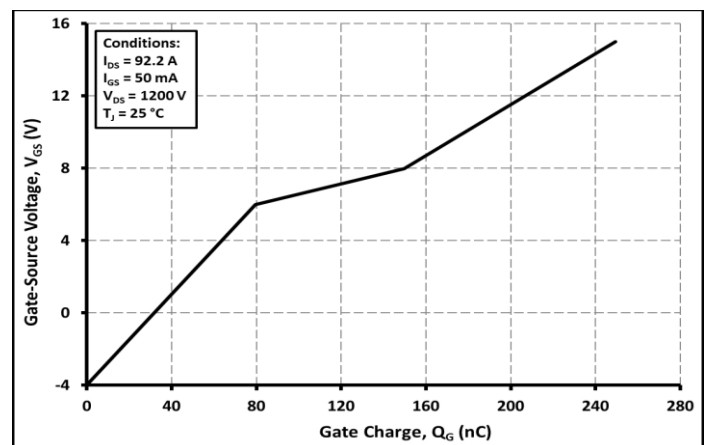


Figure 12.

Gate Charge Characteristics

## Typical Performance

All the graphs are based on a die placed in a TO-247-4L package.

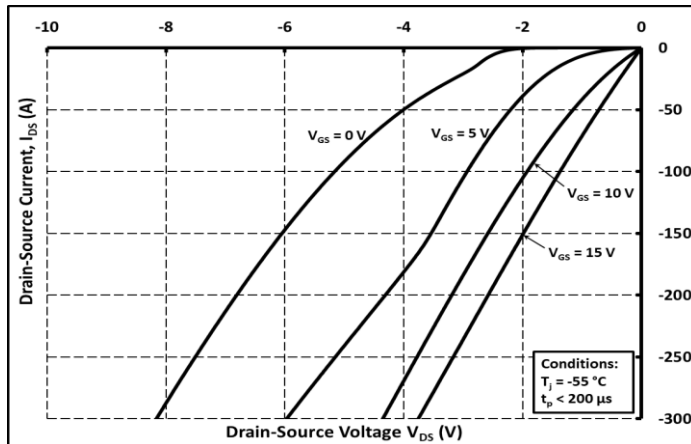


Figure 13.

3rd Quadrant Characteristic at  $T_{vj} = -55\text{ }^{\circ}\text{C}$

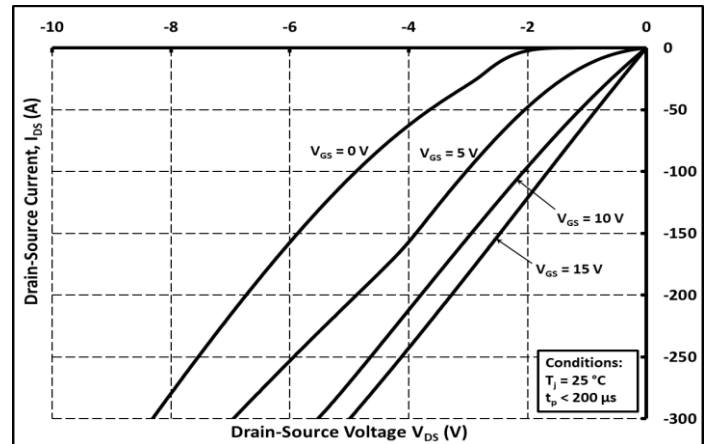


Figure 14.

3rd Quadrant Characteristic at  $T_{vj} = 25\text{ }^{\circ}\text{C}$

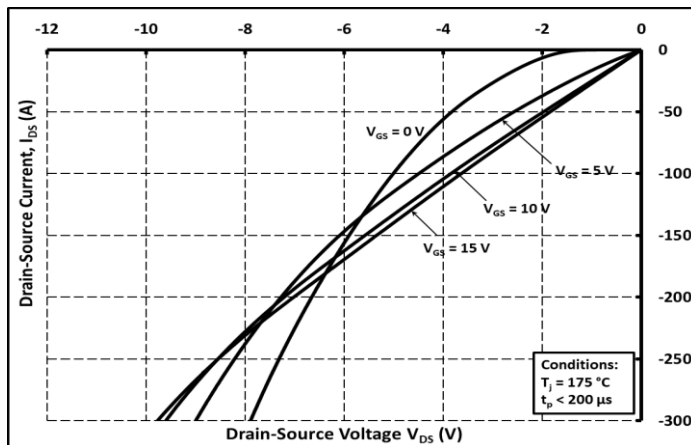


Figure 15.

3rd Quadrant Characteristic at  $T_{vj} = 175\text{ }^{\circ}\text{C}$

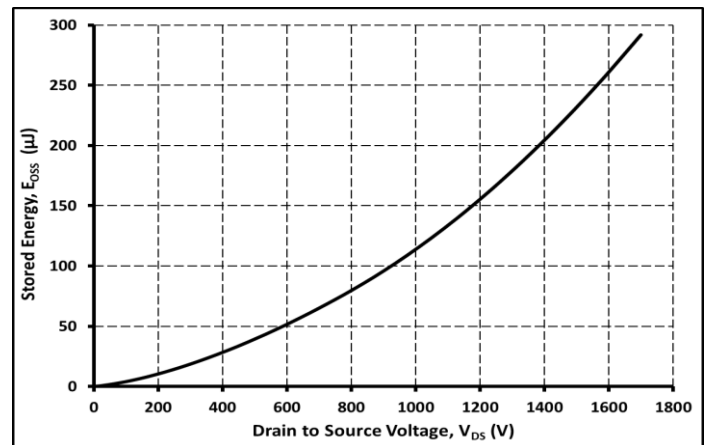


Figure 16.

Output Capacitor Stored Energy

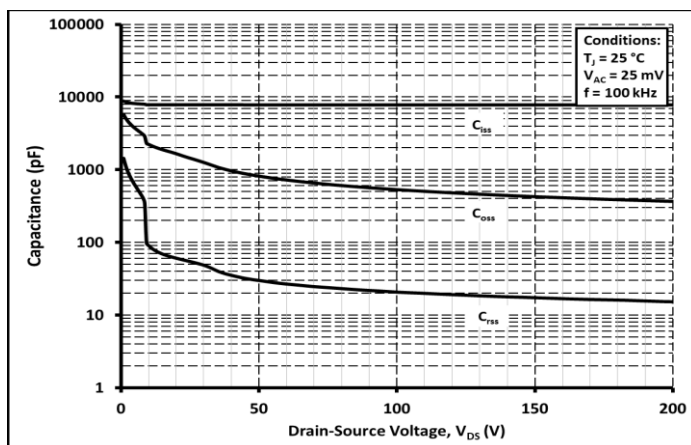


Figure 17.

Capacitances vs. Drain-Source Voltage (0-200V)

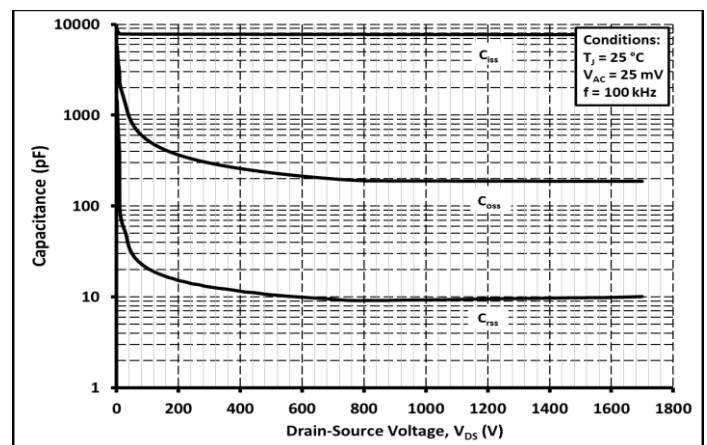
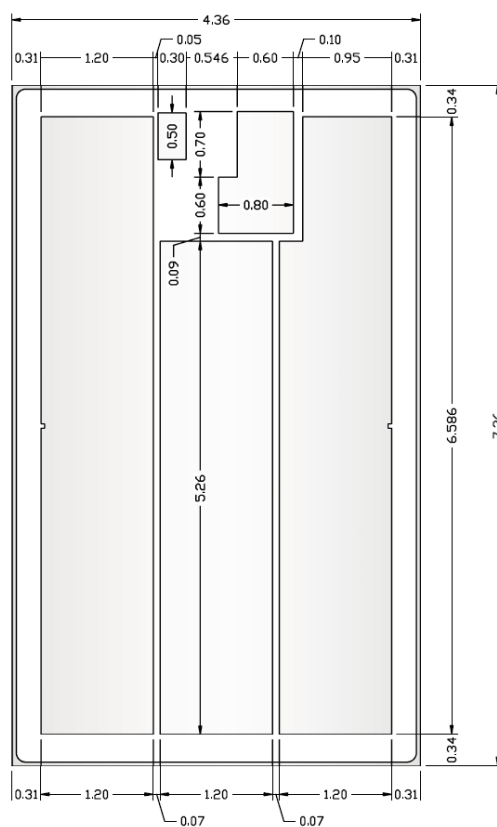


Figure 18.

Capacitances vs. Drain-Source Voltage (0-1200V)



## Product Dimensions CPM3-1700-R020E



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Parameter	Typical	Units
Die Size (L x W)	4.36 x 7.26	mm
Exposed Source Pad Metal Dimensions	1.20 x 6.59	mm
Exposed Source Pad Metal Dimensions	1.20 x 5.26 (X2)	mm
Exposed Source Pad Metal Dimensions	0.95 x 1.39	mm
Gate Pad Dimensions	0.8 x 0.6	mm
Gate Pad Dimensions	0.6 x 0.7	mm
Rg Pad Dimensions*	0.5 x 0.3	mm
Chip Thickness <sup>1</sup>	180 ± 20	μm
Frontside (Source) metalization (Al)	4	μm
Frontside (Gate) metalization (Al)	4	μm
Backside (Drain) metalization (Ni:Pd:Au)	0.8 / 0.2 / 0.1	μm

<sup>1</sup> SiC wafer thickness

\*For internal use only



Product Ordering Information

Order Number	Description	Package
CPM3-1700-R020E-FY6	SiC MOSFET G3 IND 1700V/20mO UV MLT	Bare Die Product

Revision History

Revision History	Date of Change	Brief Summary
1	09/09/2021	Initial Release
2	12/21/2023	<ul style="list-style-type: none"><li>Document format updated</li></ul>



## Notes & Disclaimer

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